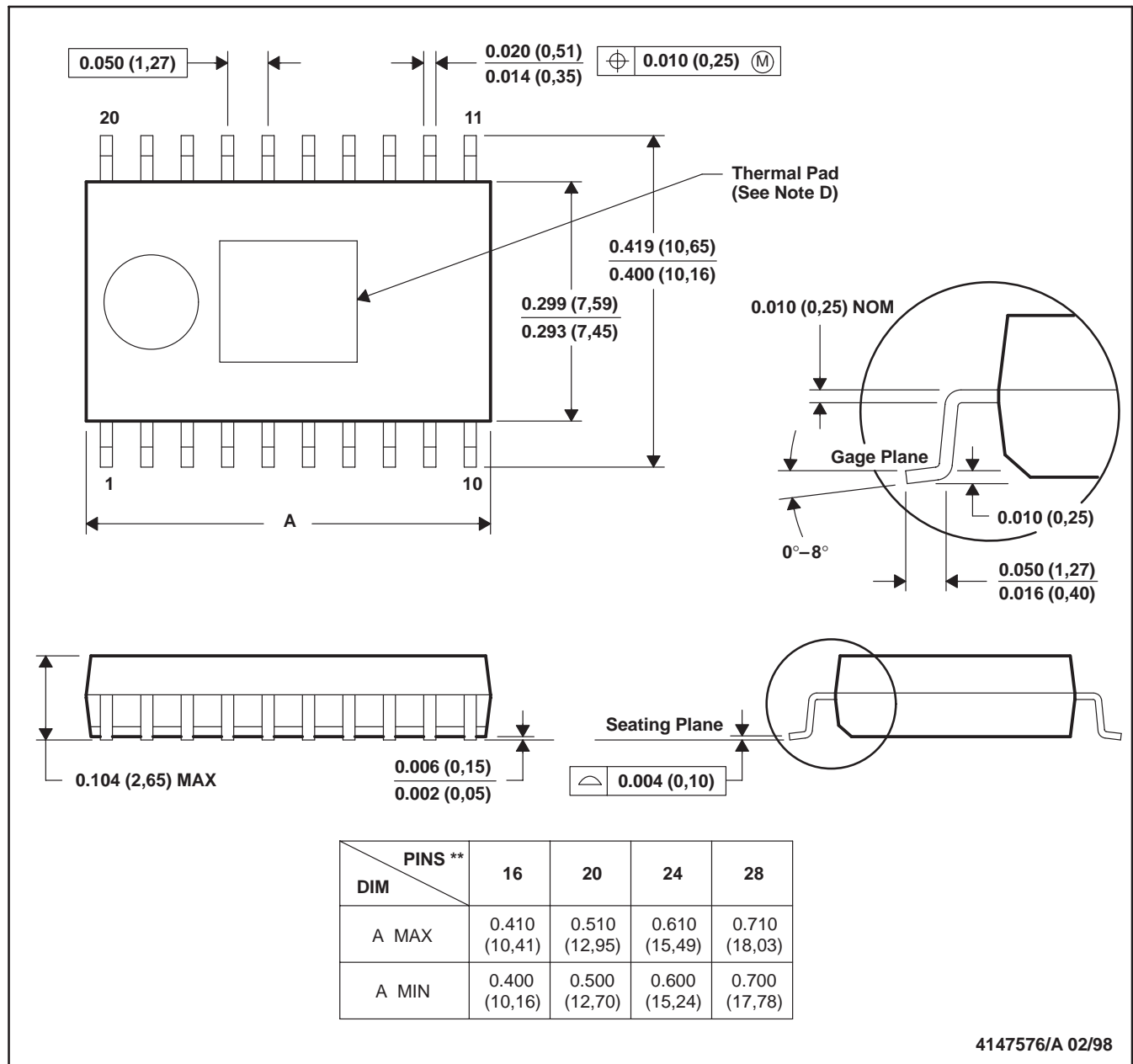


DWD (R-PDSO-G**)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE (DIE-DOWN)

20-PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. The package thermal performance may be enhanced by attaching an external heat sink to the thermal pad. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.

PowerPAD is a trademark of Texas Instruments Incorporated.

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